(4) the method for manufacturing electronic parts according to any one of (1) to (3), wherein the pasty adhesive in the semi-cured adhesive layer-forming step contains at least an epoxy resin and/or a (meth)acrylate ester.

[0007a]

In another aspect, there is provided a cohesive sheet for manufacture of electronic parts, which is used as bonded to the semi-cured adhesive layer formed on the rear face of a wafer, comprising a base film and a cohesive layer laminated on one face of the base film, wherein:

the cohesive constituting the cohesive layer contains a (meth)acrylate ester copolymer, an ultraviolet polymerizable compound, a multifunctional isocyanate curing agent and a photopolymerization initiator; and

the temperature of the photopolymerization initiator, at which the weight loss rate thereof, which is calculated by the following equation:

weight loss rate = {(mass before heating - mass after heating)/(mass before heating)}×100 (%)

(wherein, the mass before heating is the mass of the photopolymerization initiator at 25°C; the mass after heating is the mass of the photopolymerization initiator at each temperature when it is heated from 23°C to 500°C at a heating rate of 10°C /minute) becomes 10%, is 250°C or higher.

Advantageous Effects of the Invention

[0008]

According to the method for manufacturing electronic parts of the present invention, wherein the cohesive constituting the cohesive layer of cohesive sheet has a particular composition, it is possible to improve contamination resistance of the semi-cured adhesive layer formed on the semiconductor wafer and thus to suppress adhesion failure for example with the chips and the lead frame.

[0009]

Also according to the method for manufacturing electronic parts of the present invention, it is possible, in addition to the improvement of contamination resistance above, to reduce the number of chip flying during dicing and to make the cohesive sheet and the semi-cured adhesive layer readily separated from each other.

Description of Embodiments

[0010]

<Definition of terms>

The monomer unit, as used herein, means a structural unit derived from monomer. "Part" and "%" are values by mass. (Meth)acrylate is a generic term indicating both acrylate and methacrylate. (Meth)-including compounds such as (meth)acrylic acid are also generic terms indicating both a "meth"-including compound and a "meth"-free compound.